Product Information Sheet

EPO-TEK® 731

Date:	September 2017		**Recommended Cure: 80°C / 2 Hours**
Rev:	III		
No. of Components:	Two		Minimum Alternative Cure(s):
Mix Ratio by Weight:	1 : 1		*May not achieve performance properties listed below*
Specific Gravity:	Part A: 1.12	Part B: 0.97	100°C / 30 Minutes
Pot Life:	1.5 Hours		23°C / 24 Hours
Shelf Life- Bulk:	One year at room temperature		

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

Product Description: A two component, thixotropic, room temperature-curing epoxy adhesive. It is an electrically and thermally insulating epoxy designed for general applications in semiconductor packaging, electronics, medical, and optical industries. A higher viscosity version of EPO-TEK® 730.

Typical Properties: Cure condition: 80°C / 2 Hours Different batches, conditions & applications yield differing results.
Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:		
* Color (before cure):	Part A: Tan	Part B: Tan
* Consistency:	Smooth paste	
* Viscosity (23°C) @ 1 rpm:	175,000-275,000	cPs
Thixotropic Index:	N/A	
* Glass Transition Temp:	≥ 55	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	74	x 10^{-6} in/in°C
Above Tg:	168	x 10^{-6} in/in°C
Shore D Hardness:	66	
Lap Shear @ 23°C:	> 2,000	psi
Die Shear @ 23°C:	≥ 10	Kg 3,556 psi
Degradation Temp:	417	°C
Weight Loss:		
@ 200°C:	0.47	%
@ 250°C:	0.92	%
@ 300°C:	1.62	%
Suggested Operating Temperature:	< 300	°C (Intermittent)
Storage Modulus:	196,634	psi
* Particle Size:	≤ 20	microns

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	N/A	
Volume Resistivity @ 23°C:	≥ 2 x 10^{13}	Ohm-cm
Dielectric Constant (1KHz):	3.38	
Dissipation Factor (1KHz):	0.028	

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